

- STRUCTURE Silicon Monolithic Integrated Circuit
- ♦ PRODUCT I2C BUS 128Kbit (16,384 × 8bit) EEPROM
- ♦ PART NUMBER BU9897GUL-W

| PART NUMBER | PACKAGE |
|-------------|----------|
| BU9897GUL-W | VCSP50L2 |

♦ FEATURES Two wire serial interface Wide operating voltage range (1.7V~5.5V) Endurance : 1,000,000 erase/write cycles

♦ ABSOLUTE MAXIMUM RATING (Ta=25°C)

| Parameter | Symbol | Rating | | Unit |
|-----------------------|--------|--------------|----|------|
| Supply Voltage | Vcc | -0.3~6.5 | | V |
| Power Dissipation | Pd | 220 | *1 | mW |
| Storage Temperature | Tstg | -65~125 | | °C |
| Operating Temperature | Topr | -40~85 | | °C |
| Terminal Voltage | — | -0.3~Vcc+1.0 | *2 | V |

*1 2.2mW/°C(*1) for operation above $25^{\circ}C$

*2 The Max value of Terminal Voltage is not over 6.5V

♦ RECOMMENDED OPERATING CONDITION

| Parameter | Symbol | Rating | Unit |
|----------------|--------|---------|------|
| Supply Voltage | Vcc | 1.7~5.5 | V |
| Input Voltage | VIN | 0~Vcc | V |



♦ MEMORY CELL CHARACTERISTICS (Ta=25°C, Vcc=1.7~5.5V)

| Parameter | | | Unit | | |
|-------------------|----|-----------|------|------|--------|
| Parameter | | Min. | Тур. | Max. | Unic |
| Write/Erase Cycle | *1 | 1,000,000 | - | - | Cycles |
| Data Retention | *1 | 40 | - | - | Years |

OInitial Data FFh in all address.

♦ DC OPERATING CHARACTERISTICS

♦BLOCK DIAGRAM

| \$ 20 01 E10 | | | | | | | |
|---------------------------|--------|---------------|------|---------|------|---|--|
| Parameter | Symbol | Specification | | | Unit | Specification | |
| | | Min. | Min. | Min. | | • | |
| "H" Input Voltage1 | VIH1 | 0.7Vcc | | Vcc+1.0 | V | | |
| "L" Input Voltage1 | VIH2 | -0.3 | - | 0.3Vcc | V | | |
| "L" Output Voltage1 | VOL1 | - | - | 0.4 | V | IOL=3.0mA, 2.5V≦Vcc≦ 5.5V (SDA) | |
| "L" Output Voltage2 | VOL2 | - | - | 0.2 | V | IOL=0.7mA, 1.7V≦Vcc< 2.5V (SDA) | |
| Input Leakage Current | ILI | -1 | - | 1 | μA | VIN=0V~Vcc | |
| Output Leakage Current | ILO | -1 | - | 1 | μA | VOUT=0V~Vcc (SDA) | |
| Operating Current | ICC1 | _ | - | 2.5 | mA | Vcc=5.5V,fSCL=400 k Hz, tWR=5ms Byte Write,Page Write | |
| Operating Cullent | ICC2 | _ | _ | 0.5 | mA | Vcc=5.5V,fSCL=400 k Hz Random Read,Current Read,Sequential Read | |
| Standby Current | ISB | _ | — | 2.0 | μA | Vcc=5.5V,SDA,SCL=Vcc A0,A1,A2=GND,WP=GND | |

*1 Not 100% TESTED

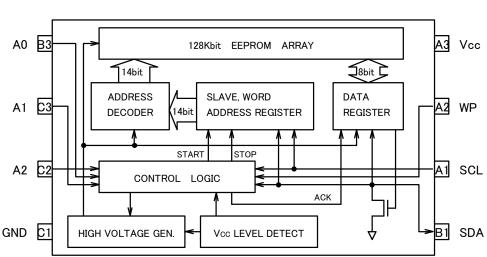
(Unless otherwise specified Ta=-40~85°C, Vcc=1.7~5.5V)

♦ AC OPERATING CHARACTERISTICS

| (0111000 0 | ittlerwise spe | | pecification | | 0.017 |
|---------------------------------------|----------------|------|--------------|------|-------|
| Parameter | Symbol | Min. | Typ. | Max. | Unit |
| Clock Frequency | fSCL | - | - | 400 | kHz |
| Data Clock High Period | tHIGH | 0.6 | - | - | μs |
| Data Clock Low Period | tLOW | 1.2 | - | | Ms |
| SDA and SCL Rise Time *1 | tR | | | 0.3 | Ms |
| SDA and SCL Fall Time *1 | tF | - | - | 0.3 | Ms |
| Start Condition Hold Time | tHD:STA | 0.6 | - | - | Ms |
| Start Condition Setup Time | tSU:STA | 0.6 | - | - | μs |
| Input Data Hold Time | tHD:DAT | 0 | - | - | ns |
| Input Data Setup Time | tSU:DAT | 100 | - | - | ns |
| Output Data Delay Time | tPD | 0.1 | - | 0.9 | μs |
| Output Data Hold Time | tDH | 0.1 | | | μs |
| Stop Condition Setup Time | tSU:STO | 0.6 | - | | μs |
| Bus Free Time | tBUF | 1.2 | - | | μs |
| Write Cycle Time | tWR | - | - | 5 | ns |
| Noise Spike Width (SDA and SCL) | tl | _ | _ | 0.1 | μs |
| WP Hold Time | tHD:WP | 0 | - | - | ns |
| WP Setup Time | tSU:WP | 0.1 | - | - | μs |
| WP High Period | tHIGH:WP | 1.0 | - | - | μs |

*1 Not 100% TESTED

♦ PIN No. NAME



| | PIN No. | PIN NAME |
|---|---------|----------|
| | A1 | SCL |
| > | A2 | WP |
| | A3 | Vcc |
| | A4 | GND |
| | B1 | SDA |
| | B3 | A0 |
| | B4 | GND |
| | C1 | GND |
| L | C2 | A2 |
| | C3 | A1 |
| | C4 | GND |
| | | |

Fig.-1 BLOCK DIAGRAM



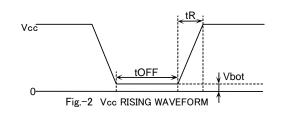
♦NOTES FOR POWER SUPPLY

Vcc rises through the low voltage region in which internal circuit of IC and the controller are unstable, so that device may not work properly due to an incomplete reset of internal circuit. To prevent this, the device has the feature of P.O.R. and LVCC. In the case of power up, keep the following conditions to ensure functions of P.O.R. and LVCC.

SCI

SDA _____ After Vcc becomes stable

- 1. It is necessary to be "SDA='H'" and "SCL='L' or 'H'".
- 2. Follow the recommended conditions of tR, tOFF, Vbot for the function of P.O.R. during power up.



♦ RECOMMENDED CONDITIONS OF tR, tOFF, Vbot

Vcc becomes stable

+SU DAT

Fig.-3(b) SCL='L' and SDA='L'

tLOW

tDH 'tSU:DAT

Fig.-3(a) SCL='H' and SDA='L'

3. Prevent SDA and SCL from being "High-Z".

In case that condition 1. and/or 2. cannot be met, take following actions.

A) Unable to keep condition 1.

(SDA is "LOW" during power up.)

 \rightarrow Control SDA ,SCL to be "HIGH" as Fig.-3(a),

3(b).

B)Unable to keep condition 2.

→After power becomes stable, execute

C)Unable to keep both conditions 1 and 2.

 \rightarrow Follow the instruction A first, then the instruction B.

♦ CAUTIONS ON USE

(1) Absolute maximum ratings

If the absolute maximum ratings such as impressed voltage and action temperature range and so forth are exceeded, LSI may be destructed. Do not impress voltage and temperature exceeding the absolute maximum ratings. In the case of fear exceeding the absolute maximum ratings, take physical safety countermeasures such as fuses, and see to it that conditions exceeding the absolute maximum ratings should not be impressed to LSI.

(2) GND electric potential

Set the voltage of GND terminal lowest at any action condition. Make sure that each terminal voltage is not lower than that of GND terminal.

(3) Thermal design

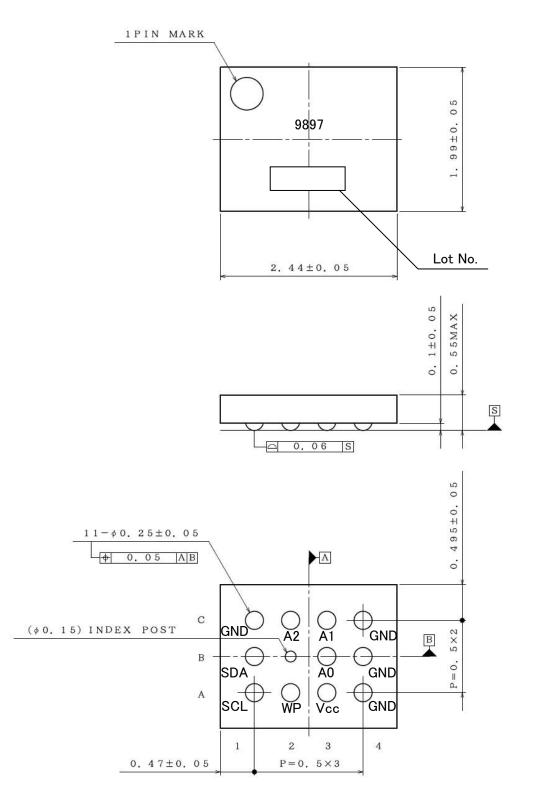
In consideration of permissible loss in actual use condition, carry out heat design with sufficient margin.

(4) Terminal to terminal shortcircuit and wrong packaging

When to package LSI onto a board, pay sufficient attention to LSI direction and displacement. Wrong packaging may destruct LSI. And in the case of shortcircuit between LSI terminals and terminals and power source, terminal and GND owing to foreign matter, LSI may be destructed.

(5) Use in a strong electromagnetic field may cause malfunction, therefore, evaluated design sufficiently.





The A4, B4, C4 pins are set to GND inside chip. Please set these OPEN. Please don't connect these GND.

(UNIT:mm)

Drawing No:EX912-5052

Fig.-1 PHYSICAL DIMENSION (UNIT:mm)

4/4

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